

Kester® EP256HA

No-Clean Solder Paste

Designed to provide maximum print performance characteristics and solderability with lead-free parts requiring leaded solder paste

Kester EP256HA is a no-clean, air or nitrogen reflowable solder paste. It is specifically designed to provide optimal print performance and solderability on lead-free parts when leaded solder paste is required. EP256HA has been developed for applications that require the ultimate activity with respect to difficult to solder to components and board surface metalizations.



Key Features

- Excellent printing characteristics to 0.4 mm (16 mil) pitch with Type 3 powder and is capable of up to 90-minute break times in printing
- High print speeds to 150 mm/s (6 in/s)
- Excellent solderability on difficult to solder to components, i.e., Pd/Ag high activity on all substrates, including OSPs
- Stable tack and stencil life of over 8 hours (process set up dependent)
- Classified as ROL0 per J-STD-004



For more information, contact us at
Assembly@MacDermidAlpha.com

